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MullishPATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Skala et al. Examiner: Im, J. M.
Serial No.: 09/874,606 Group Art Unit: 2811
Filed: June 5, 2001 Docket No.: PHA 51243A
Title: PAD METALIZATION OVER ACTIVE CIRCUITRY

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence and the papers, as described hereinabove, are being transmitted via facsimile only-Formal Entry, to the attention of Examiner Im Assistant Commissioner for Patents, Washington, D.C. 20231, on February 3, 2003.

Facsimile No. (703) 872-9319

By: Kelly F. Waltigney

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OFFICE ACTION AMENDMENT AND RESPONSE AFTER FINAL

BOX AF
Assistant Commissioner for Patents
Washington, D.C. 20231

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Sir:

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In response to the Final Office Action dated December 4, 2002, please reconsider the above-referenced application for patent in view of the following amendments and remarks.

In the Claims:

Please replace the indicated claims as follows; a marked-up version of the claim amendments is attached hereto.

- OK to enter
Im
15. (Amended) A semiconductor chip having circuitry, the semiconductor chip comprising:
- a metal bond pad over a portion of the circuitry;
 - a diffusion barrier layer over the metal bond pad; and
 - a metal layer over the diffusion barrier layer, the metal layer being configured and arranged for connecting to a wire bond, and the metal bond pad, the diffusion barrier layer and the metal layer all being insulated on at least two sides by passivation material;
- wherein the diffusion layer is constructed and arranged to mitigate inter-metallic compounds forming as a reaction to the metal layer connecting to the wire bond, and the